

# RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	APR '03	31326	0310 NSEB	DJ232810AAB	SOIC	50	50	0

# RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	JAN '03	30753	0249 Hana	DU218037AA	SOIC	50	50	0
DS1621	A7	MAR '03	30969	0237 OSEP	DE106688AAB	SOIC	50	50	0

# RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28532	0126	ATP (Amkor, PI)	DK114601AD	SOIC	1	4	0
DS1100	A3	JAN '02	28611	0132	ATP (Amkor, PI)	DK115002AK	SOIC	1	4	0
DS1100	A3	JUL '02	30189	0230	OSEP	DE120202AFB	SOIC	1	4	0
DS1100	A3	JAN '03	30767	0243	Carsem	DM242094AJC	SOIC	1	4	0
DS1100	A3	APR '03	31251	0312	ATP (Amkor, PI)	DK242100AH	SOIC	1	4	0
DS1232	C2-L	JUL '02	30182	0111	OSEP	DE049638ADB	SOIC	1	4	0
DS1232	C2-L	JAN '03	30755	0252	ATP (Amkor, PI)	DK235629AB	SOIC	1	4	0
DS1232	C2-L	APR '03	31299	0310	Carsem	DM304031AH	SOIC	1	4	0
DS1233	A5-5	APR '03	31306	0311	Hana	DU321432DC	SOT223	1	4	0
DS1267	A1	AUG '02	30196	0237	Carsem	DM234023AF	TSSOP	5	4	0
DS1267	A1	APR '03	31313	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	5	4	0
DS1620	D1	JAN '03	30747	0249	Hana	DU218037AA	SOIC	7	4	0
DS1621	A7	MAR '03	30963	0237	OSEP	DE106688AAB	SOIC	7	4	0
DS1803	A2	OCT '02	30226	0234	ATP (Amkor, PI)	DK236047AA	SOIC	2	4	0
DS1803	A2	APR '03	31258	0304	OSEP	DE322628AAB	SOIC	2	4	0
DS2118M	C1-6	MAR '03	31032	0233	ATK (Amkor, K)	DN108304AB	SSOP	6	4	0
DS21352	A4	AUG '02	30216	0240	Stats	DC039494AA	LQFP	2	4	0
DS21352	A4	FEB '03	31026	0242	ATP (Amkor, PI)	DK036653AA	LQFP	2	4	0
DS21352	A4	MAY '03	31398	0312	Stats	DC043465AA	LQFP	2	4	0
DS2154	A2	NOV '02	30233	0230	Stats	DC102671AA	LQFP	2	4	0
DS21Q43	A3-	FEB '03	30955	0305	ATK (Amkor, K)	DN039537AA	LQFP	1	4	0
DS2502	C4	JUL '02	30107	0238	OSEP	DE252080AEB	TSOC	2	4	0

# RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C4	JAN '03	30762	0249 OSEP	DE303581AAB	TSOC	2	4	0
DS2502	C4	APR '03	31265	0310 OSEP	DE311138AM	TSOC	2	4	0
DS87C520	A15-	DEC '02	30252	0232 ATP (Amkor, PI)	DK241602AA	PLCC	2	4	0

## RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	JAN '03	30745	0231	Fastech	331980	Module w/Bent Fra	300	100	0
DS12887	A2-	APR '03	31297	0311	Fastech	334654	Module w/Bent Fra	300	100	0
DS1990	J3-F	FEB '03	31053	0301	Fastech	334146-1	iButton F50w/IC's	500	77	0
DS1990	J3-F	MAY '03	31396	0304	Fastech	334377-1	iButton F50w/IC's	500	77	0
DS1992	E7-F	JUN '03	31653	0315	Fastech	335226-1	iButton F50 w/Bum	500	77	0
DS29020	A7-3	MAR '03	31049	0252	Dallas	DX310061AAA	Cartridge	300	77	0
DS29020	A7-3	JUN '03	31645	0317	Consonic T	DX327020AAA	Cartridge	300	77	0
DS3832	B-C	+ DS3802	30849	0215	Dallas	964558-1	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	30849	0215	Dallas	964558-1	BGA Module, 1 Sid	1000	8	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28536	0126	ATP (Amkor, PI)	DK114601AD	SOIC	300	40	0
DS1100	A3	OCT '01	28536	0126	ATP (Amkor, PI)	DK114601AD	SOIC	1000	40	0
DS1100	A3	JAN '02	28615	0132	ATP (Amkor, PI)	DK115002AK	SOIC	300	40	0
DS1100	A3	JAN '02	28615	0132	ATP (Amkor, PI)	DK115002AK	SOIC	1000	40	0
DS1100	A3	JUL '02	30193	0230	OSEP	DE120202AFB	SOIC	500	40	0
DS1100	A3	JUL '02	30193	0230	OSEP	DE120202AFB	SOIC	1000	40	0
DS1100	A3	JAN '03	30771	0243	Carsem	DM242094AJC	SOIC	500	40	0
DS1100	A3	JAN '03	30771	0243	Carsem	DM242094AJC	SOIC	1000	40	0
DS1100	A3	APR '03	31255	0312	ATP (Amkor, PI)	DK242100AH	SOIC	500	40	0
DS1232	C2-L	JUL '02	30186	0111	OSEP	DE049638ADB	SOIC	500	40	0
DS1232	C2-L	JUL '02	30186	0111	OSEP	DE049638ADB	SOIC	1000	40	0
DS1232	C2-L	JAN '03	30759	0252	ATP (Amkor, PI)	DK235629AB	SOIC	500	40	0
DS1232	C2-L	JAN '03	30759	0252	ATP (Amkor, PI)	DK235629AB	SOIC	1000	40	0
DS1232	C2-L	APR '03	31303	0310	Carsem	DM304031AH	SOIC	500	40	0
DS1233	A5-5	APR '03	31310	0311	Hana	DU321432DC	SOT223	1000	40	0
DS1267	A1	AUG '02	30200	0237	Carsem	DM234023AF	TSSOP	500	40	0
DS1267	A1	AUG '02	30200	0237	Carsem	DM234023AF	TSSOP	1000	40	0
DS1620	D1	JAN '03	30751	0249	Hana	DU218037AA	SOIC	500	40	0
DS1620	D1	JAN '03	30751	0249	Hana	DU218037AA	SOIC	1000	40	0
DS1620	D1	APR '03	31324	0310	NSEB	DJ232810AAB	SOIC	500	40	0
DS1620	D1	APR '03	31324	0310	NSEB	DJ232810AAB	SOIC	1000	40	0
DS1621	A7	MAR '03	30967	0237	OSEP	DE106688AAB	SOIC	500	40	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	MAR '03	30967	0237	OSEP	DE106688AAB	SOIC	1000	40	0
DS1803	A2	OCT '02	30230	0234	ATP (Amkor, PI)	DK236047AA	SOIC	500	40	0
DS1803	A2	APR '03	31262	0304	OSEP	DE322628AAB	SOIC	500	40	0
DS2118M	C1-6	MAR '03	31036	0233	ATK (Amkor, K)	DN108304AB	SSOP	500	77	0
DS2118M	C1-6	MAR '03	31036	0233	ATK (Amkor, K)	DN108304AB	SSOP	1000	77	0
DS21352	A4	AUG '02	30220	0240	Stats	DC039494AA	LQFP	500	77	0
DS21352	A4	AUG '02	30220	0240	Stats	DC039494AA	LQFP	1000	77	0
DS21352	A4	FEB '03	31030	0242	ATP (Amkor, PI)	DK036653AA	LQFP	500	80	9
DS21352	A4	MAY '03	31402	0312	Stats	DC043465AA	LQFP	500	80	7
DS21352	A4	MAY '03	31402	0312	Stats	DC043465AA	LQFP	1000	73	0
DS2154	A2	NOV '02	30237	0230	Stats	DC102671AA	LQFP	500	78	0
DS2154	A2	NOV '02	30237	0230	Stats	DC102671AA	LQFP	1000	78	0
DS2401	C2	MAY '03	31648	0323	Carsem	DM330002AA	TO92	500	45	0
DS2502	C4	JUL '02	30110	0238	OSEP	DE252080AEB	TSOC	500	77	0
DS2502	C4	JUL '02	30110	0238	OSEP	DE252080AEB	TSOC	1000	77	0
DS2502	C4	JAN '03	30765	0249	OSEP	DE303581AAB	TSOC	500	77	0
DS2502	C4	JAN '03	30765	0249	OSEP	DE303581AAB	TSOC	1000	77	0
DS2502	C4	APR '03	31268	0310	OSEP	DE311138AM	TSOC	500	77	0
DS2502	C4	APR '03	31268	0310	OSEP	DE311138AM	TSOC	1000	77	0
DS80C320	C5	DEC '02	30260	0230	ATP (Amkor, PI)	DK240563AB	PDIP	500	45	0
DS80C320	C5	DEC '02	30260	0230	ATP (Amkor, PI)	DK240563AB	PDIP	1000	45	0
DS87C520	A15-	DEC '02	30256	0232	ATP (Amkor, PI)	DK241602AA	PLCC	500	50	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS87C520	A15-	DEC '02	30256	0232 ATP (Amkor, PI)	DK241602AA	PLCC	1000	50	0

# RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	FEB '03	31041	0305 Dallas	334458	Module w/Hi Densit	500	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1620	D1	JAN '03	30754	0249	Hana	DU218037AA	SOIC	500	50	0
DS1620	D1	JAN '03	30754	0249	Hana	DU218037AA	SOIC	1000	50	0
DS1620	D1	APR '03	31327	0310	NSEB	DJ232810AAB	SOIC	500	50	0
DS1620	D1	APR '03	31327	0310	NSEB	DJ232810AAB	SOIC	1000	50	0
DS1621	A7	MAR '03	30970	0237	OSEP	DE106688AAB	SOIC	500	50	0
DS1621	A7	MAR '03	30970	0237	OSEP	DE106688AAB	SOIC	1000	50	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	FEB '03	31040	0305	Dallas	334458	Module w/Hi Densit	500	77	0
DS1643	C1	FEB '03	31040	0305	Dallas	334458	Module w/Hi Densit	1000	77	0
DS1643	C1	MAY '03	31391	0317	Fastech	335494	Module w/Hi Densit	500	77	0
DS1990	J3-F	FEB '03	31052	0301	Fastech	334146-1	iButton F50w/IC's	500	77	0
DS1990	J3-F	FEB '03	31052	0301	Fastech	334146-1	iButton F50w/IC's	1000	77	0
DS1990	J3-F	MAY '03	31395	0304	Fastech	334377-1	iButton F50w/IC's	500	77	0
DS1990	J3-F	MAY '03	31395	0304	Fastech	334377-1	iButton F50w/IC's	1000	77	0
DS1992	E7-F	JUN '03	31652	0315	Fastech	335226-1	iButton F50 w/Bum	500	77	0

# RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS29020	A7-3	MAR '03	31048	0252 Dallas	DX310061AAA	Cartridge	336	75	0
DS29020	A7-3	JUN '03	31644	0317 Consonic T	DX327020AAA	Cartridge	336	77	0
DS3832	B-C	+ DS3802	30848	0215 Dallas	964558-1	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	30848	0215 Dallas	964558-1	BGA Module, 1 Sid	1000	8	0

# RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: JESD22-B102

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	JAN '03	30743	0231 Fastech	331980	Module w/Bent Fra	1	3	0
DS12887	A2-	APR '03	31295	0311 Fastech	334654	Module w/Bent Fra	1	3	0
DS1643	C1	FEB '03	31038	0305 Dallas	334458	Module w/Hi Densit	5	3	0
DS1643	C1	MAY '03	31389	0317 Fastech	335494	Module w/Hi Densit	5	3	0

# RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					CODE	FACILITY	POINT
DS1100	A3	OCT '01	28534	0126	ATP (Amkor, PI)	DK114601AD	SOIC	1	4	0
DS1100	A3	JAN '02	28613	0132	ATP (Amkor, PI)	DK115002AK	SOIC	1	4	0
DS1100	A3	JUL '02	30191	0230	OSEP	DE120202AFB	SOIC	1	4	0
DS1100	A3	JAN '03	30769	0243	Carsem	DM242094AJC	SOIC	1	4	0
DS1100	A3	APR '03	31253	0312	ATP (Amkor, PI)	DK242100AH	SOIC	1	4	0
DS1232	C2-L	JUL '02	30184	0111	OSEP	DE049638ADB	SOIC	7	4	0
DS1232	C2-L	JAN '03	30757	0252	ATP (Amkor, PI)	DK235629AB	SOIC	7	4	0
DS1232	C2-L	APR '03	31301	0310	Carsem	DM304031AH	SOIC	7	4	0
DS1233	A5-5	APR '03	31308	0311	Hana	DU321432DC	SOT223	2	4	0
DS1267	A1	AUG '02	30198	0237	Carsem	DM234023AF	TSSOP	2	4	0
DS1267	A1	APR '03	31315	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	2	4	0
DS1620	D1	JAN '03	30749	0249	Hana	DU218037AA	SOIC	7	4	0
DS1620	D1	APR '03	31322	0310	NSEB	DJ232810AAB	SOIC	7	4	0
DS1621	A7	MAR '03	30965	0237	OSEP	DE106688AAB	SOIC	7	4	0
DS1803	A2	OCT '02	30228	0234	ATP (Amkor, PI)	DK236047AA	SOIC	2	4	1
DS1803	A2	APR '03	31260	0304	OSEP	DE322628AAB	SOIC	2	4	0
DS2118M	C1-6	MAR '03	31034	0233	ATK (Amkor, K)	DN108304AB	SSOP	6	4	0
DS21352	A4	AUG '02	30218	0240	Stats	DC039494AA	LQFP	5	4	0
DS21352	A4	FEB '03	31028	0242	ATP (Amkor, PI)	DK036653AA	LQFP	5	4	1
DS21352	A4	MAY '03	31400	0312	Stats	DC043465AA	LQFP	5	4	0
DS2154	A2	NOV '02	30235	0230	Stats	DC102671AA	LQFP	5	4	0
DS2502	C4	JUL '02	30109	0238	OSEP	DE252080AEB	TSOC	2	4	0

# RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C4	JAN '03	30764	0249 OSEP	DE303581AAB	TSOC	2	4	1
DS2502	C4	APR '03	31267	0310 OSEP	DE311138AM	TSOC	2	4	0
DS87C520	A15-	DEC '02	30254	0232 ATP (Amkor, PI)	DK241602AA	PLCC	2	4	0

# RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: JESD22-B100

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	JAN '03	30744	0231 Fastech	331980	Module w/Bent Fra	1	6	0
DS12887	A2-	APR '03	31296	0311 Fastech	334654	Module w/Bent Fra	1	6	0
DS1643	C1	FEB '03	31039	0305 Dallas	334458	Module w/Hi Densit	5	6	0
DS1643	C1	MAY '03	31390	0317 Fastech	335494	Module w/Hi Densit	5	6	0

# RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	FEB '03	31042	0305	Dallas	334458	Module w/Hi Densit	500	77	13
DS1990	J3-F	FEB '03	31054	0301	Fastech	334146-1	iButton F50w/IC's	500	77	0
DS1990	J3-F	FEB '03	31054	0301	Fastech	334146-1	iButton F50w/IC's	1000	77	0
DS1990	J3-F	MAY '03	31397	0304	Fastech	334377-1	iButton F50w/IC's	500	77	0
DS1990	J3-F	MAY '03	31397	0304	Fastech	334377-1	iButton F50w/IC's	1000	77	0
DS3832	B-C	+ DS3802	30850	0215	Dallas	964558-1	BGA Module, 1 Sid	500	8	0
DS3832	B-C	+ DS3802	30850	0215	Dallas	964558-1	BGA Module, 1 Sid	1000	8	0

# RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 85 C/85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS29020	A7-3	MAR '03	31050	0252 Dallas	DX310061AAA	Cartridge	274	77	0
DS29020	A7-3	JUN '03	31646	0317 Consonic T	DX327020AAA	Cartridge	274	77	0

# RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS21352	A4	AUG '02	30221	0240	Stats	DC039494AA	LQFP	96	72	0
DS21352	A4	FEB '03	31031	0242	ATP (Amkor, PI)	DK036653AA	LQFP	96	78	7
DS21352	A4	MAY '03	31403	0312	Stats	DC043465AA	LQFP	96	77	7
DS2154	A2	NOV '02	30238	0230	Stats	DC102671AA	LQFP	200	77	0

# RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	JUL '02	30187	0111 OSEP	DE049638ADB	SOIC	96	77	0
DS1232	C2-L	JAN '03	30760	0252 ATP (Amkor, PI)	DK235629AB	SOIC	96	77	2
DS1232	C2-L	APR '03	31304	0310 Carsem	DM304031AH	SOIC	96	77	0

# RELIABILITY MONITOR

STRESS: EXTERNAL VISUAL

CONDITIONS: JESD22-B101

PRODUCT	REV	MONITOR	DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	POINT	QTY	FAIL
		DATE	JOB NO	CODE FACILITY						
DS3832	B-C	+ DS3802	30849	0215 Dallas	964558-1	BGA Module, 1 Sid	6	8	0	

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS3832	B-C	+ DS3802	30846	0215 Dallas	964558-1	BGA Module, 1 Sid	2	24	3
DS87C520	A15-	DEC '02	30253	0232 ATP (Amkor, PI)	DK241602AA	PLCC	3	239	0

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE	ASSEMBLY	LOT NO.	PACKAGE	READ		
		DATE	JOB NO					CODE	FACILITY	POINT
DS1100	A3	OCT '01	28533	0126	ATP (Amkor, PI)	DK114601AD	SOIC	3	238	0
DS1100	A3	JAN '02	28612	0132	ATP (Amkor, PI)	DK115002AK	SOIC	3	238	0
DS1100	A3	JUL '02	30190	0230	OSEP	DE120202AFB	SOIC	3	241	0
DS1100	A3	JAN '03	30768	0243	Carsem	DM242094AJC	SOIC	3	241	0
DS1100	A3	APR '03	31252	0312	ATP (Amkor, PI)	DK242100AH	SOIC	3	241	0
DS1232	C2-L	JUL '02	30183	0111	OSEP	DE049638ADB	SOIC	3	241	0
DS1232	C2-L	JAN '03	30756	0252	ATP (Amkor, PI)	DK235629AB	SOIC	3	241	0
DS1232	C2-L	APR '03	31300	0310	Carsem	DM304031AH	SOIC	3	241	0
DS1233	A5-5	APR '03	31307	0311	Hana	DU321432DC	SOT223	3	241	0
DS1267	A1	AUG '02	30197	0237	Carsem	DM234023AF	TSSOP	3	241	0
DS1267	A1	APR '03	31314	0309	ATP (Amkor, PI)	DK236020AFA	TSSOP	3	241	0
DS1620	D1	JAN '03	30748	0249	Hana	DU218037AA	SOIC	3	244	0
DS1620	D1	APR '03	31321	0310	NSEB	DJ232810AAB	SOIC	3	244	0
DS1621	A7	MAR '03	30964	0237	OSEP	DE106688AAB	SOIC	3	240	0
DS1803	A2	OCT '02	30227	0234	ATP (Amkor, PI)	DK236047AA	SOIC	3	241	0
DS1803	A2	APR '03	31259	0304	OSEP	DE322628AAB	SOIC	3	241	0
DS21352	A4	AUG '02	30217	0240	Stats	DC039494AA	LQFP	3	241	0
DS21352	A4	FEB '03	31027	0242	ATP (Amkor, PI)	DK036653AA	LQFP	3	241	0
DS21352	A4	MAY '03	31399	0312	Stats	DC043465AA	LQFP	3	241	1
DS2154	A2	NOV '02	30234	0230	Stats	DC102671AA	LQFP	3	241	0
DS2502	C4	JUL '02	30108	0238	OSEP	DE252080AEB	TSOC	3	151	0
DS2502	C4	JAN '03	30763	0249	OSEP	DE303581AAB	TSOC	3	151	0

# RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2502	C4	APR '03	31266	0310 OSEP	DE311138AM	TSOC	3	151	0

## RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28537	0126	ATP (Amkor, PI)	DK114601AD	SOIC	500	77	0
DS1100	A3	OCT '01	28537	0126	ATP (Amkor, PI)	DK114601AD	SOIC	1000	75	0
DS1100	A3	JAN '02	28616	0132	ATP (Amkor, PI)	DK115002AK	SOIC	500	77	0
DS1100	A3	JAN '02	28616	0132	ATP (Amkor, PI)	DK115002AK	SOIC	1000	77	0
DS1100	A3	JUL '02	30194	0230	OSEP	DE120202AFB	SOIC	500	77	0
DS1100	A3	JUL '02	30194	0230	OSEP	DE120202AFB	SOIC	1000	77	0
DS1100	A3	JAN '03	30772	0243	Carsem	DM242094AJC	SOIC	500	77	0
DS1100	A3	JAN '03	30772	0243	Carsem	DM242094AJC	SOIC	1000	77	0
DS1100	A3	APR '03	31256	0312	ATP (Amkor, PI)	DK242100AH	SOIC	500	77	0
DS1267	A1	AUG '02	30201	0237	Carsem	DM234023AF	TSSOP	500	77	0
DS1267	A1	AUG '02	30201	0237	Carsem	DM234023AF	TSSOP	1000	77	0
DS12887	A2-	JAN '03	30746	0231	Fastech	331980	Module w/Bent Fra	500	100	0
DS12887	A2-	JAN '03	30746	0231	Fastech	331980	Module w/Bent Fra	1000	100	0
DS12887	A2-	APR '03	31298	0311	Fastech	334654	Module w/Bent Fra	500	100	1
DS1620	D1	JAN '03	30752	0249	Hana	DU218037AA	SOIC	500	70	0
DS1620	D1	JAN '03	30752	0249	Hana	DU218037AA	SOIC	1000	70	0
DS1620	D1	APR '03	31325	0310	NSEB	DJ232810AAB	SOIC	500	70	0
DS1620	D1	APR '03	31325	0310	NSEB	DJ232810AAB	SOIC	1000	70	0
DS1621	A7	MAR '03	30968	0237	OSEP	DE106688AAB	SOIC	500	70	0
DS1621	A7	MAR '03	30968	0237	OSEP	DE106688AAB	SOIC	1000	70	0
DS80C320	C5	DEC '02	30261	0230	ATP (Amkor, PI)	DK240563AB	PDIP	500	77	0
DS80C320	C5	DEC '02	30261	0230	ATP (Amkor, PI)	DK240563AB	PDIP	1000	77	0

# RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1100	A3	OCT '01	28538	0126	ATP (Amkor, PI)	DK114601AD	SOIC	168	40	0
DS1100	A3	JAN '02	28617	0132	ATP (Amkor, PI)	DK115002AK	SOIC	168	39	0
DS1100	A3	JUL '02	30195	0230	OSEP	DE120202AFB	SOIC	168	40	0
DS1100	A3	JAN '03	30773	0243	Carsem	DM242094AJC	SOIC	168	40	0
DS1100	A3	APR '03	31257	0312	ATP (Amkor, PI)	DK242100AH	SOIC	168	39	0
DS1232	C2-L	JUL '02	30188	0111	OSEP	DE049638ADB	SOIC	168	40	0
DS1232	C2-L	JAN '03	30761	0252	ATP (Amkor, PI)	DK235629AB	SOIC	168	40	0
DS1232	C2-L	APR '03	31305	0310	Carsem	DM304031AH	SOIC	168	40	0
DS1233	A5-5	APR '03	31312	0311	Hana	DU321432DC	SOT223	168	40	0
DS1267	A1	AUG '02	30202	0237	Carsem	DM234023AF	TSSOP	96	40	5
DS1302	A4	JUN '03	31643	0321	OSEP	DE117012AA	PDIP	168	45	0
DS2118M	C1-6	MAR '03	31037	0233	ATK (Amkor, K)	DN108304AB	SSOP	168	77	0
DS2401	C2	MAY '03	31650	0323	Carsem	DM330002AA	TO92	168	45	0
DS2502	C4	JUL '02	30111	0238	OSEP	DE252080AEB	TSOC	96	70	0
DS2502	C4	JAN '03	30766	0249	OSEP	DE303581AAB	TSOC	168	70	0
DS2502	C4	APR '03	31269	0310	OSEP	DE311138AM	TSOC	168	70	0
DS80C320	C5	DEC '02	30262	0230	ATP (Amkor, PI)	DK240563AB	PDIP	96	45	0

# RELIABILITY MONITOR

STRESS: 0 HR TEST

CONDITIONS: Connect Cap & Base

PRODUCT	REV	MONITOR	DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	POINT	QTY	FAIL
		DATE	JOB NO	CODE FACILITY						
DS3832	B-C	+ DS3802	30847	0215 Dallas	964558-1	BGA Module, 1 Sid	1	24	0	